AMENDMENT UNDER 37 C.F.R. § 1.312

Serial Number: 10/606,539 Filing Date: June 26, 2003

Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING

Page 2 Dkt: 303.533US2

## In the Specification

Please amend the paragraph on page 1, line 5 as follows:

This application is a divisional of U.S. Application No. 09/144307 filed on August 31, 1998, now U.S. Patent No. 6,586,835, which is incorporated herein by reference.